

PCB Manufacturing Notes

General Info

Board dimensions – 40mm x 50mm
Number of layers – 2
Smallest hole – 0.3mm
Number of holes – Approx 132
Minimum Track & Gap – 0.15mm
RoHS/Lead Free – Yes
Material – FR4 or equivalent

Stackup

Stackup is to be as follows:

Layer	Copper Weight (Pre–Plating)
Layer 01 (Top)	0.5oz
Layer 02 (Bottom)	0.5oz

Finished board thickness to be 1.6mm ±0.1mm

Impedance Control

Not required.

Copper Thieving/Balancing

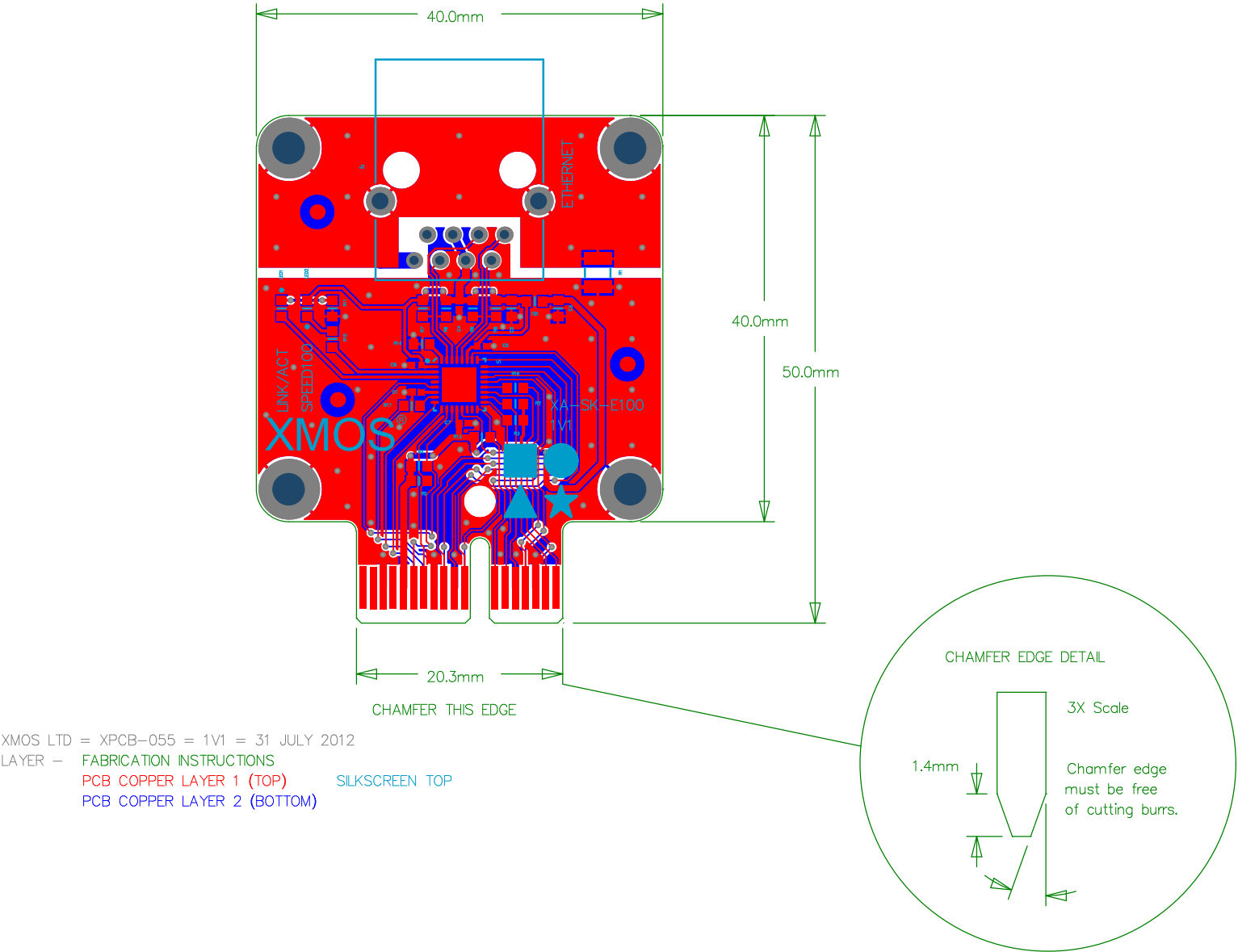
The supplier may not add copper thieving/balancing.

Finish

- A.) Conductive finish
Plating to be immersion gold.
- B.) Soldermask
Liquid photo imageable soldermask (green). Pads have not been oversized.
Supplier should oversize soldermask on pads to suit process.
- C.) Silkscreen
Colour white. Supplier should remove any silkscreen which overhangs pads.

Drill Data

Drill data is in Excellon format, metric (000.000), no zero suppression, absolute coordinates.
Hole size is finished size.



Project Name
XPCB-055 (XA-SK-E100)

Sheet	Date	Revision
A4	31 JULY 2012	1V1

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Not required.

Copper Thieving/Balancing

The supplier may not add copper thieving/balancing.

Finish

A.) Conductive finish

Plating to be immersion gold.

B.) Soldermask

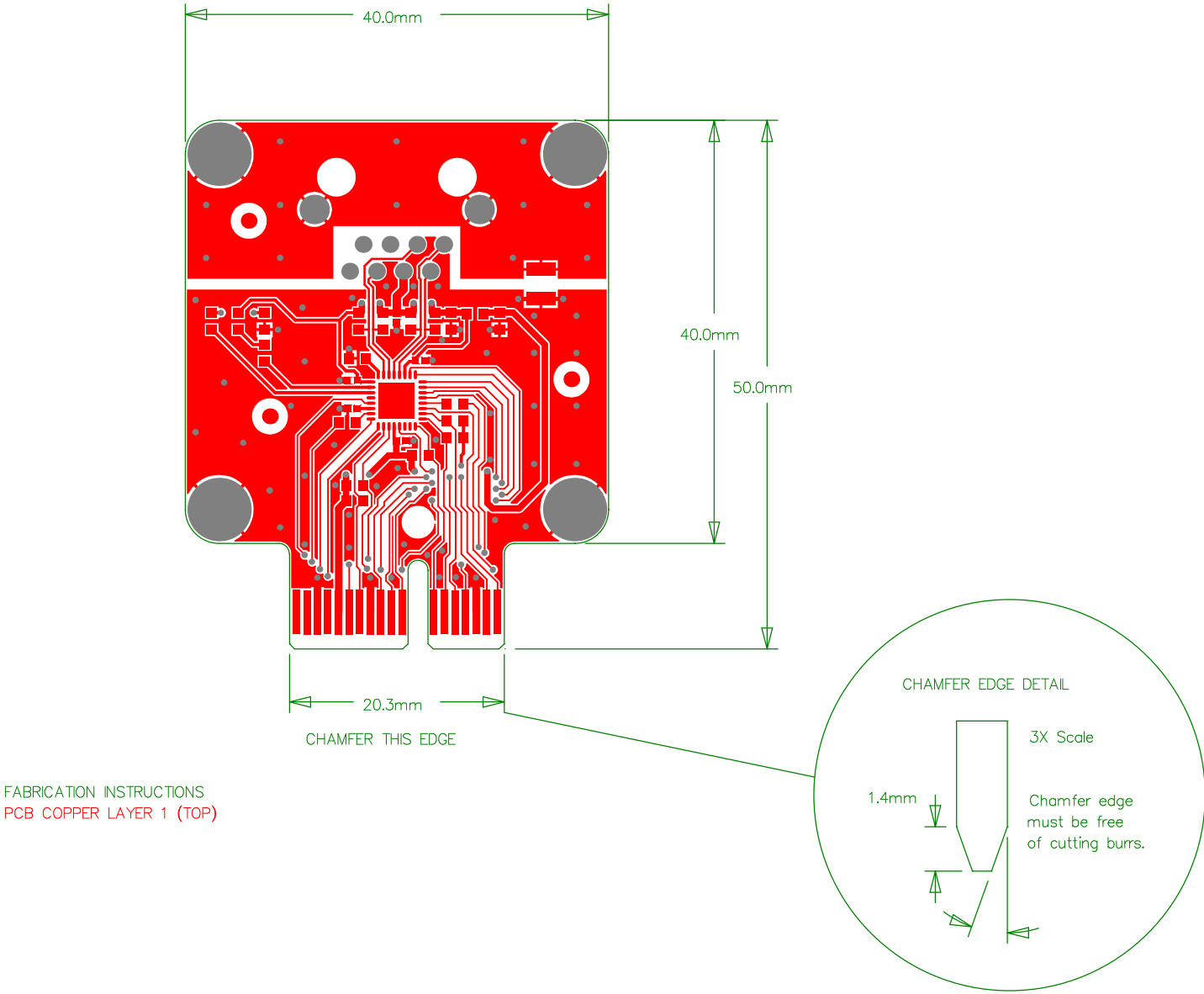
Liquid photo imageable soldermask (green). Pads have not been oversized.
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	0.5oz
Layer 02 (Bottom)	0.5oz

Finished board thickness to be 1.6mm ±0.1mm

Impedance Control

Not required.

Copper Thieving/Balancing

The supplier may not add copper thieving/balancing.

Finish

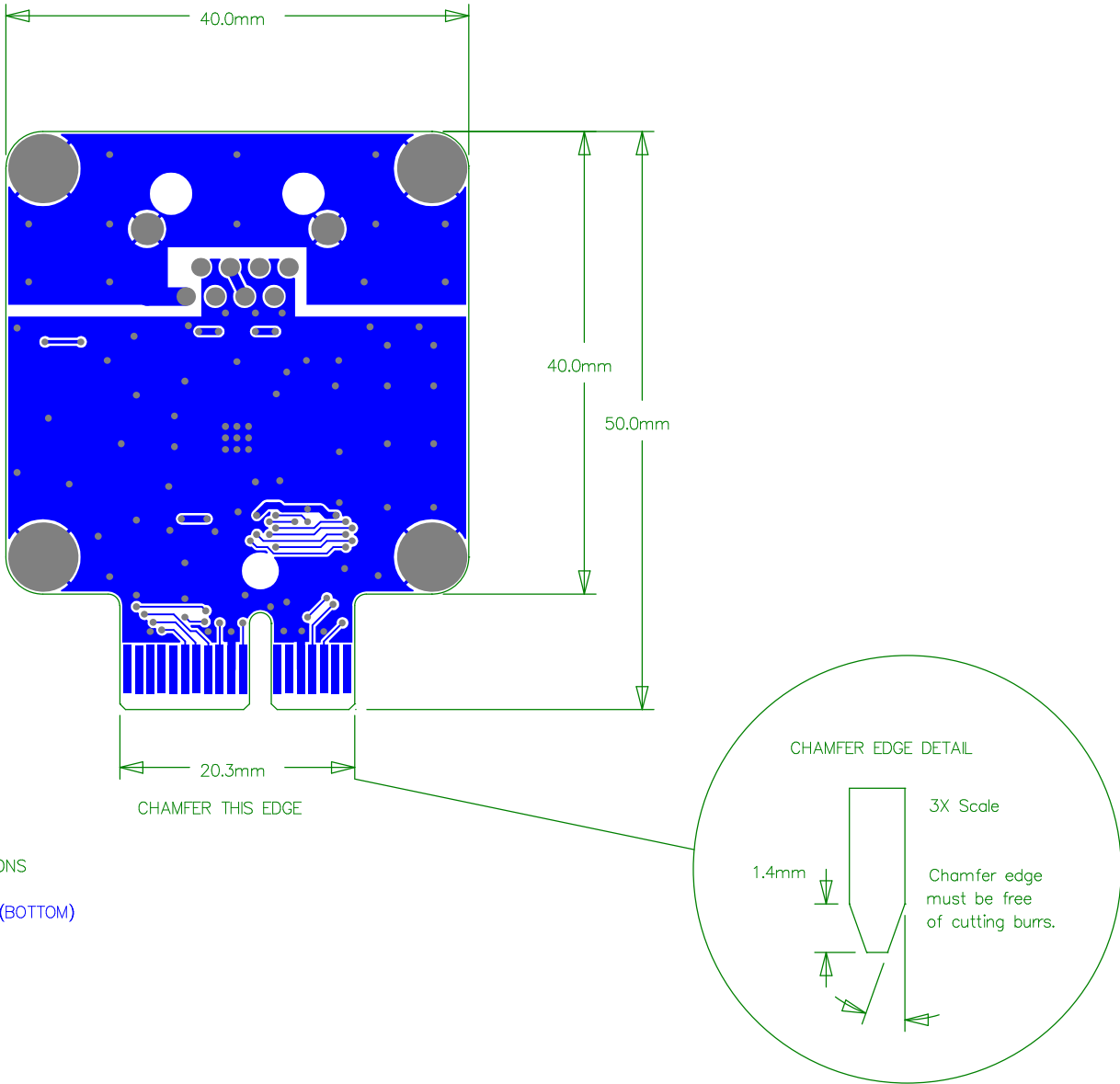
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FABRICATION INSTRUCTIONS

PCB COPPER LAYER 2 (BOTTOM)



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Finished board thickness to be 1.6mm ±0.1mm

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Copper Thieving/Balancing

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Finish

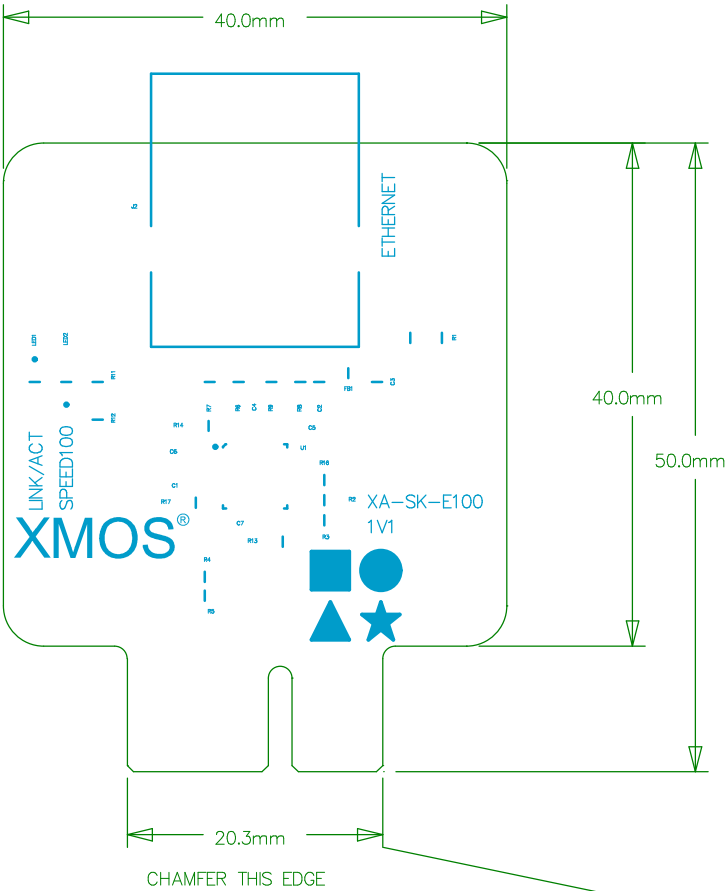
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FABRICATION INSTRUCTIONS

SILKSCREEN TOP



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Plating to be immersion gold.

B.) Soldermask

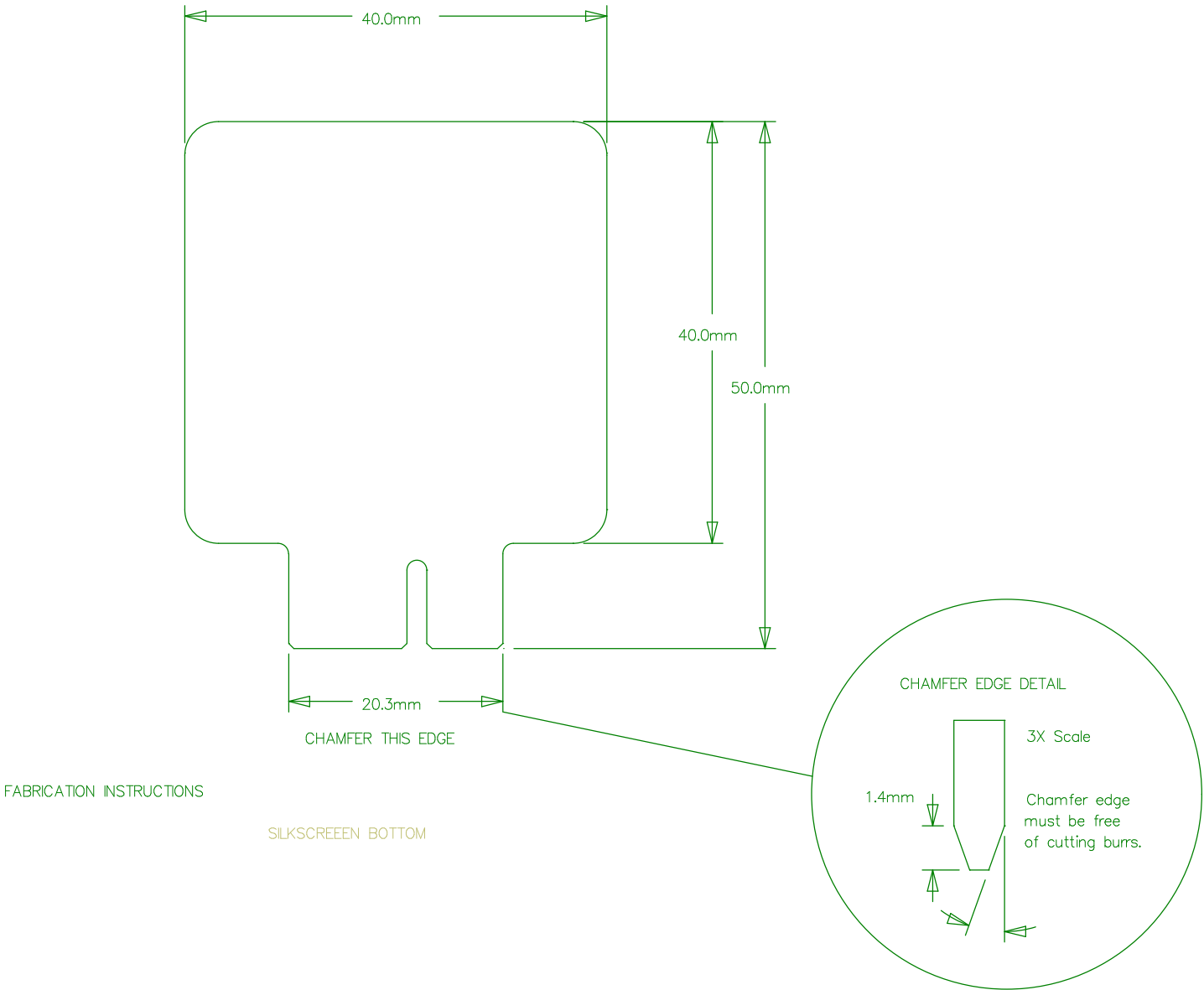
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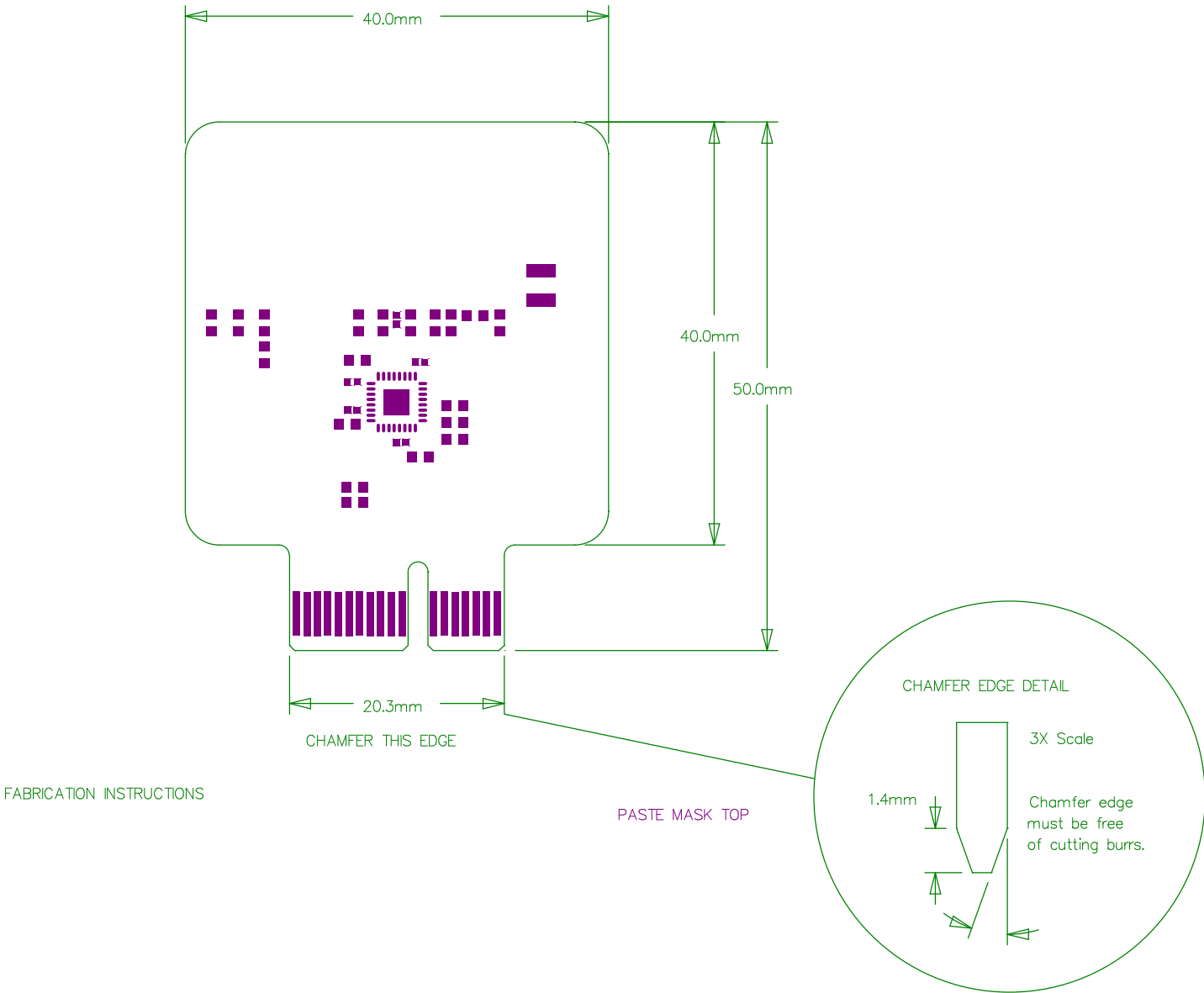
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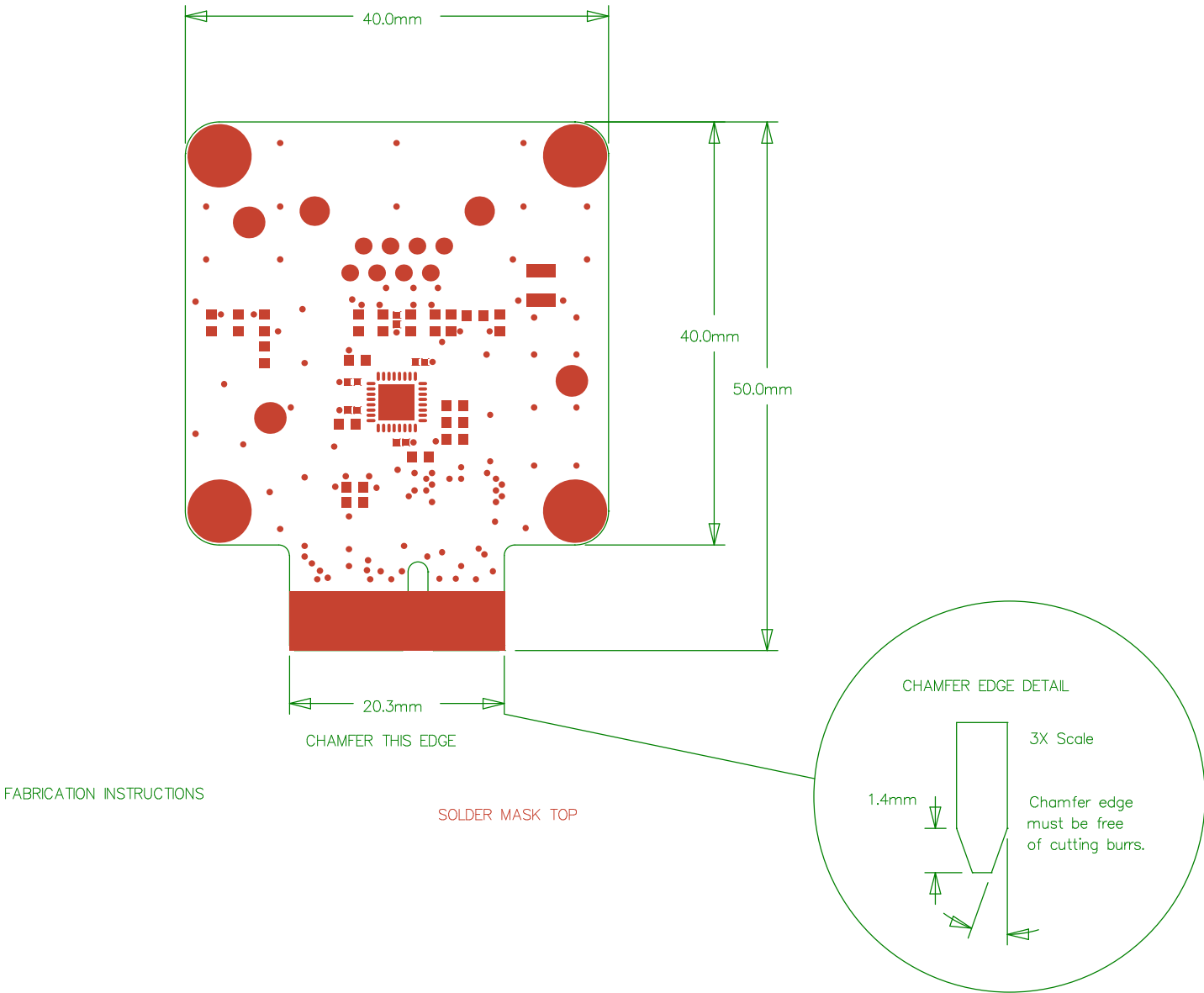
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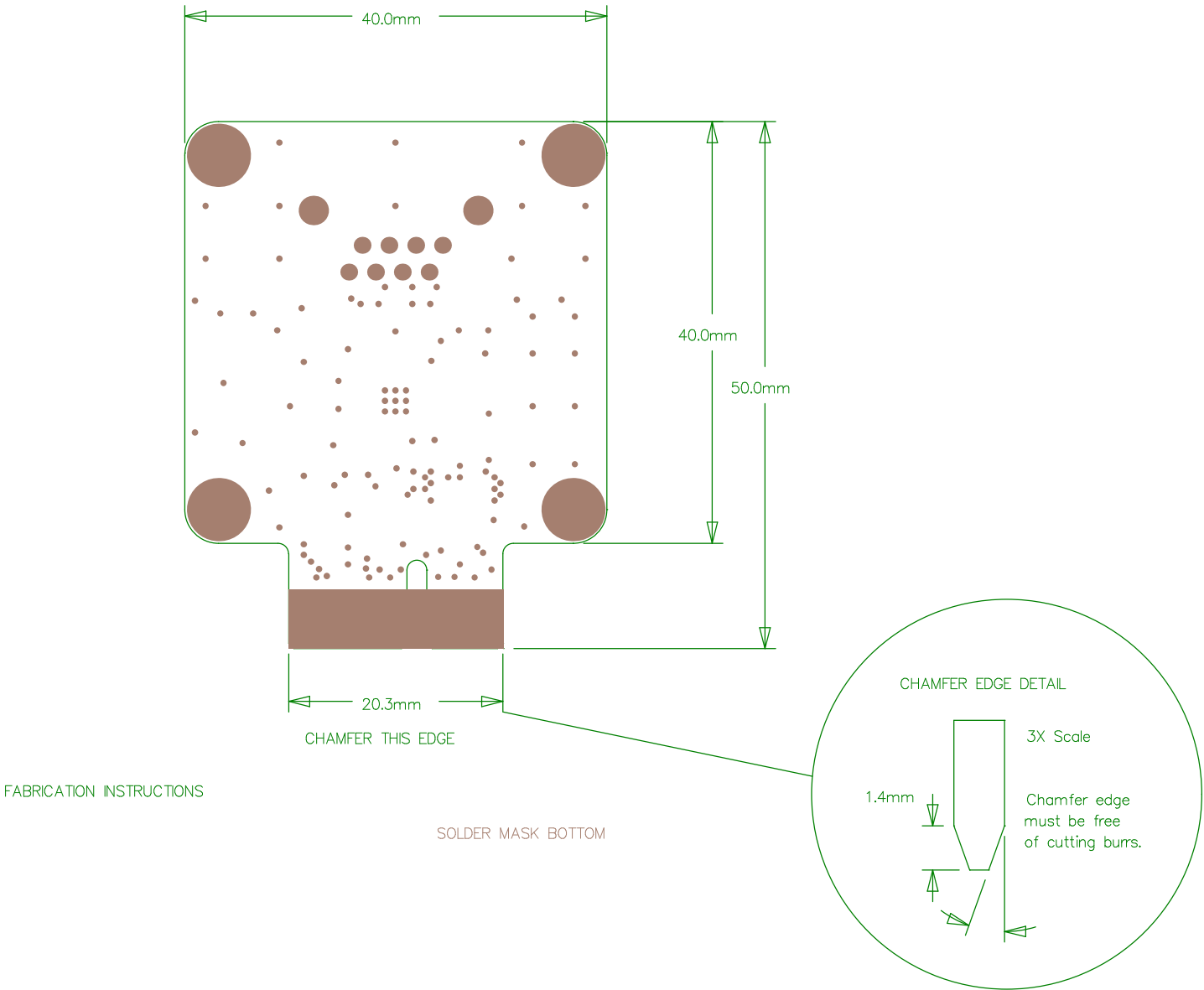
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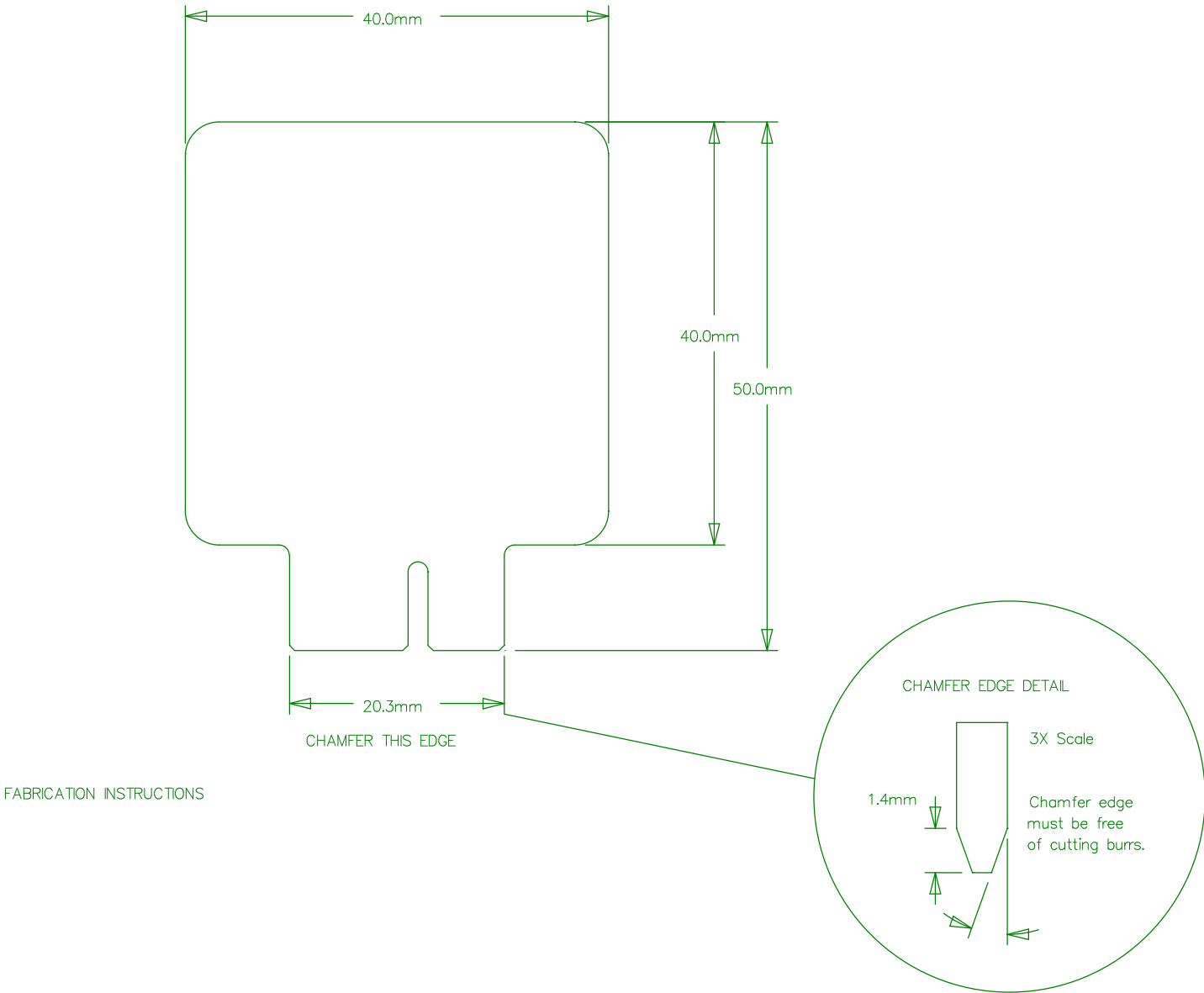
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FABRICATION INSTRUCTIONS

DRILL DRAWING

ASSEMBLY DRAWING TOP
ASSEMBLY DRAWING BOTTOM

ASSEMBLY DRAWING TOP
ASSEMBLY DRAWING BOTTOM

ASSEMBLY DRAWING TOP
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ASSEMBLY DRAWING BOTTOM

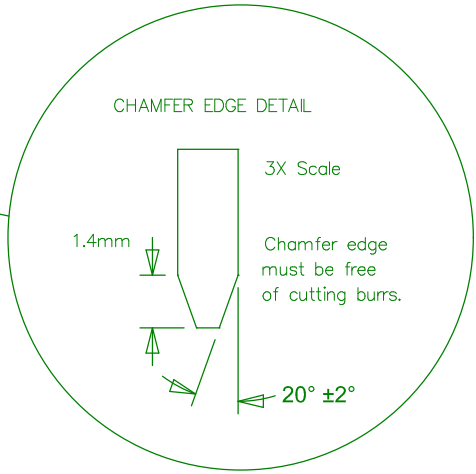
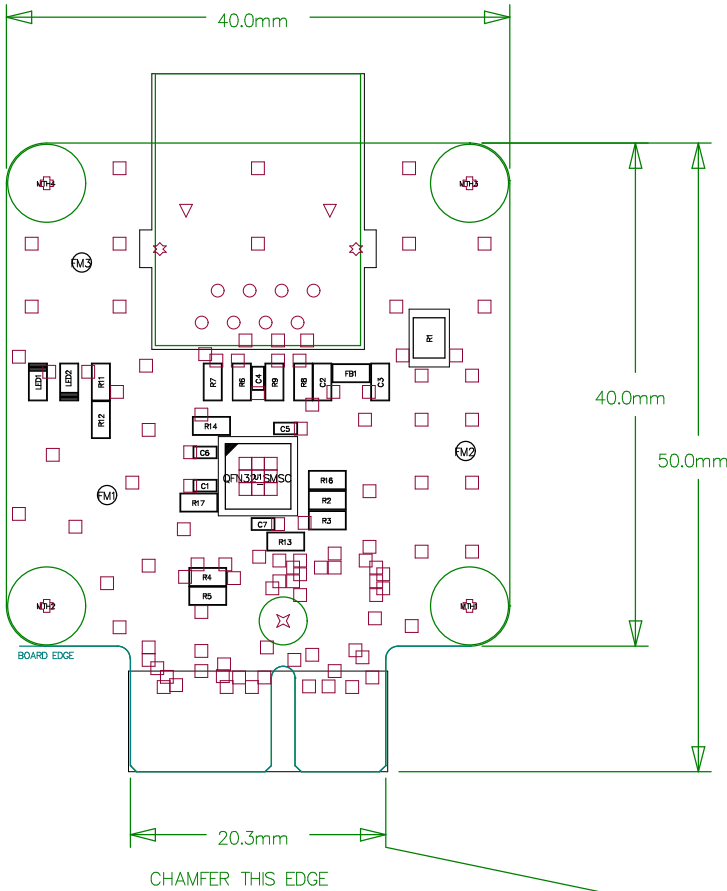
ASSEMBLY DRAWING TOP
ASSEMBLY DRAWING BOTTOM

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ASSEMBLY DRAWING BOTTOM

ASSEMBLY DRAWING TOP
ASSEMBLY DRAWING BOTTOM

ASSEMBLY DRAWING TOP
ASSEMBLY DRAWING BOTTOM

ASSEMBLY DRAWING TOP
ASSEMBLY DRAWING BOTTOM



Symbol	Hit Count	Tool Size	Plated	Hole Type
□	115	0.3mm (11.811mil)	PTH	Round
○	8	0.9mm (35.433mil)	PTH	Round
✱	2	1.65mm (64.961mil)	PTH	Round
✕	1	2.8mm (110.236mil)	NPTH	Round
⊕	4	3.2mm (125.984mil)	PTH	Round
▽	2	3.25mm (127.953mil)	NPTH	Round
	132 Total			

Drill Drawing.

XMOS®

Project Name
XPCB-055 (XA-SK-E100)

Sheet A4	Date 31 JULY 2012	Revision 1V1
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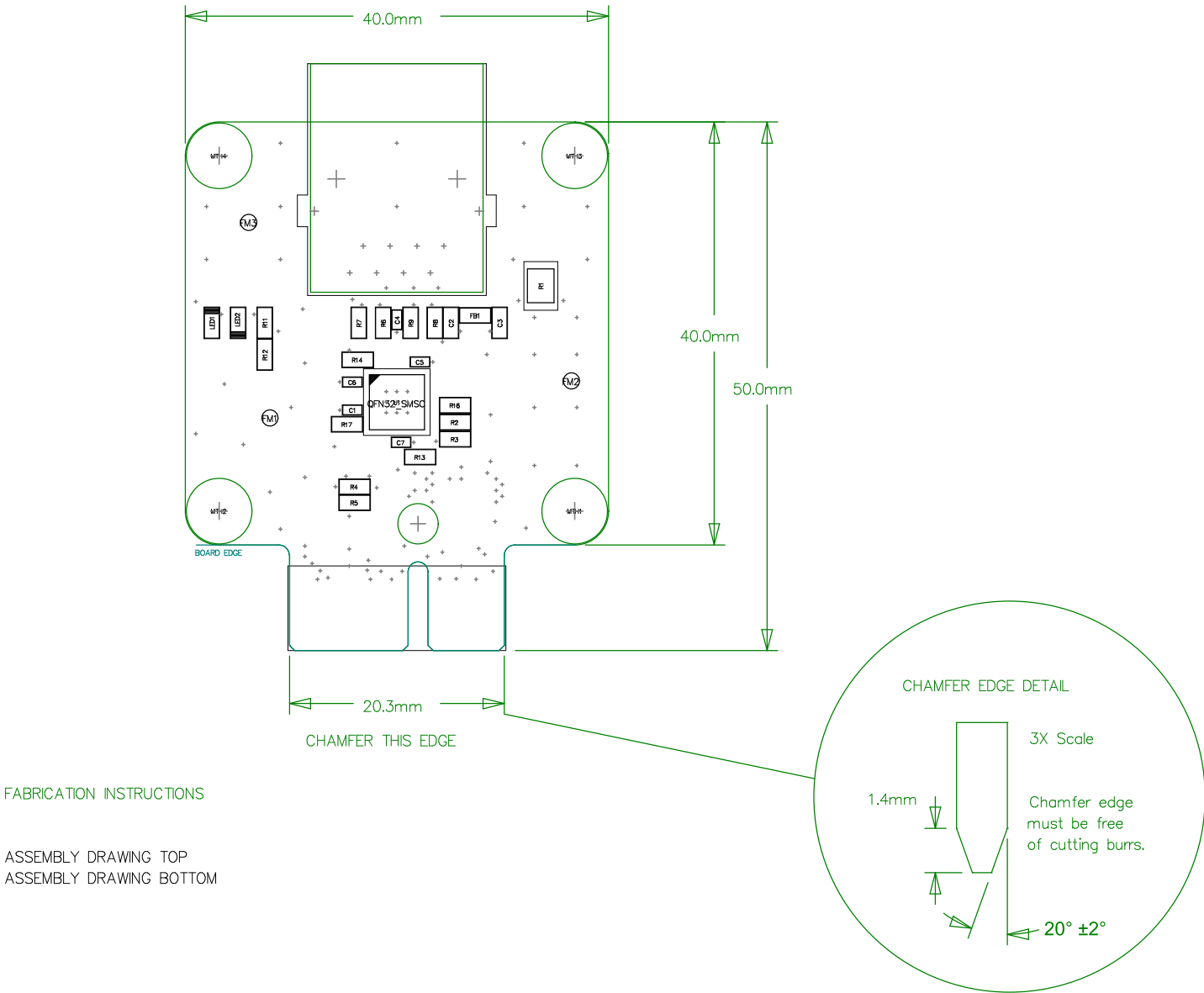
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FABRICATION INSTRUCTIONS

ASSEMBLY DRAWING TOP
ASSEMBLY DRAWING BOTTOM



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XPCB-055 (XA-SK-E100)

Sheet	Date	Revision
A4	31 JULY 2012	1V1

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BOM

E100 Ethernet Slice

Source Data From:

Project:

Variant:

XA-SK-E100.SchDoc

XPCB-055_XA-SK-E100.PrjPCB

None



Report Date:

07/12/2012

11:48:58

Print Date:

07-Dec-12

11:49:02 AM

#	LibRef	Designator	Description	Quantity
1	E-01-0002	R2, R3, R4, R5	RES 10k 0603 1%	4
2	E-01-0006	R6, R7, R8, R9	RES 49.9R 0603 1%	4
3	E-01-0008	R16, R17	RES 33R 0603 1%	2
4	E-01-0011	R13	RES 1.5k 0603 1%	1
5	E-01-0022	R11, R12	RES 470R 0603 1%	2
6	E-01-0053	R14	RES 12.1k 0603 1%	1
7	E-01-0155	R1	RES 0R 1210	1
8	E-02-0001	C1	MLCC 1uF 0402 X5R 6.3V	1
9	E-02-0002	C4, C5, C6, C7	MLCC 100nF 0402 X7R 16V	4
10	E-02-0005	C2, C3	MLCC 4.7uF 0603 X5R 6.3V	2
11	E-04-0069	J2	Ethernet Jack, Integrated Magnetics, No LEDs, THT	1
12	E-08-0001	FB1	Ferrite Bead, 470R AT 100MHz, 0603, 0.5A	1
13	E-12-0001	LED1, LED2	LED, GREEN, 0603	2
14	E-13-0033	U1	Ethernet Transceiver, 10/100, MII/RMII, QFN32	1
15	P-01-0011	PROD1, PROD2, PROD3, PROD4	Feet, Nylon, M3, 6mm Standoff	4
Approved			Notes	31